

NEWS—APRIL 15, 2009

## Belani set for April 23 CPMT talk

**The IEEE's CPMT Santa Clara Valley chapter will present industry veteran Jack Belani at the group's April 23 luncheon at the Biltmore, 2151 Laurelwood Rd., Santa Clara.**

Belani will discuss how the semiconductor packaging industry has attempted to use Cu wire in place of Au wire for several decades.

**These attempts in the past have been made each time the industry was under severe cost pressures during cyclical downturns. However in the past (pre-2004) attempts, the industry was unable to get adequate traction towards getting the critical mass for this transition, Belani says.**

Since the year 2004, as the price of gold has escalated, there has been a tremendous effort to reduce costs and Cu wire bonding has become a number 1 priority towards the cost reduction efforts. This presentation reviews the status of Cu wire and discusses its potential and issues.



*Jack Belani*

**Belani is currently the vice president of marketing and sales at Heraeus. He started his career at National Semiconductor where he spent 19 years in a variety of roles in the backend of semiconductor packaging and assembly. Belani holds a masters in materials and metallurgical engineering from the Illinois Institute of Technology and a bachelors in chemical engineering from The Indian Institute of Technology.**

Registration is at 11:30 AM; Buffet lunch will be served from 11:45-12:15 (\$15 if reserved by April 20; \$20 at door; vegetarian available); presentation begins at 12:15

[<http://www.cpmt.org/scv/>]